

ET1845A

End Termination

Description

ET1845A is a silver end termination designed for axial and radial lead attachment to MLCC (multilayer ceramic chip capacitors). ET1845A offers excellent solderability and adhesion. ET1845A is supplied at a rheology suitable for machine dip application.

Key Features

- Suitable rheology for machine dip application Excellent solderability



This picture does not show the packaging of ET1845A and is solely intended for illustration purposes. The products are available in different packaging configurations and may change over time. Please refer to the latest safety data sheets for safety-relevant pictograms.

Typical Properties

Viscosity	35 – 45 Kcps, Brookfield RVT SC4 – 14 spindle and 6R cup at 10 rpm, 25 °C
Solids	76.0 ± 1.0 %
Alloy Ratio	100
Metal	Ag

Recommended Processing Guide

Drying Temperature	150 °C peak drying profile 10 minutes at peak temperature 20 minutes total cycle time
Process Temperature (TDS)	780 °C peak temperature Dwell time of 4 – 6 minutes
Recommended Thinner	RV-372

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Warranty

6 months

Storage

Store in a dry location at 5 – 25 °C.

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